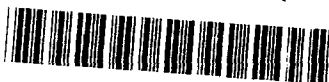




07-30-2004



102802609

ASSIGNMENT RECORD
-PATENTS ONLY-

/ER SHEET

7.7604

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)

- a) Jeffrey S. Lille
- b) Son Van Nguyen
- c) Hugo Alberto Emilio Santini

2. Name and address of receiving party(ies):

- a) Name: Hitachi Global Storage Technologies Netherlands B.V.
- Address: Locatellikade 1
Parnassustoren
1076 AZ Amsterdam
The Netherlands

3. Nature of conveyance

- | | |
|--|--|
| <input checked="" type="checkbox"/> Assignment | <input type="checkbox"/> Merger |
| <input type="checkbox"/> Security Agreement | <input type="checkbox"/> Change of Name |
| <input type="checkbox"/> Other _____ | <input type="checkbox"/> License Agreement |

Execution Date: May 5, 2004, May 24, 2004, and June 28, 2004

4. Application Number(s) or Patent Number(s): 10/837,386

The title of the (new) application is:

**HIGH ASPECT RATIO CO-PLANAR STRUCTURE FABRICATION CONSISTING OF
DIFFERENT MATERIALS**

5. Please send all correspondence concerning this (these) documents to:

Silicon Valley IP Group, PC
P.O. Box 721120
San Jose, California 95172-1120

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- ☐ Enclosed
- ☒ Authorized to be charged to Deposit Account No. 50-2587
(Order No. SJO920010161US1/HIT1P074)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date:

7/26/04

Ronald B. Feece
Registration No. 46,327

07/29/2004 NGETACHE 00000083 502587 10837386

01 FC:8021 40.00 DA

Attorney Docket No. HIT1P074/SJO920010161US1

(Revised 01/96)

**ASSIGNMENT OF PATENT APPLICATION**

(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set forth in the patent application entitled:


**HIGH ASPECT RATIO CO-PLANAR STRUCTURE FABRICATION
CONSISTING OF DIFFERENT MATERIALS**

(Atty. Docket No.: HIT1P074/SJ0920010161US1) for which I (we) have executed an application for a United States Letters Patent.

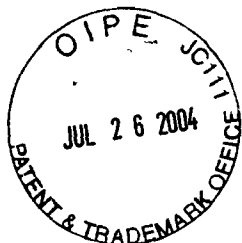
For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/we the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to **Hitachi Global Storage Technologies Netherlands B.V.**, a corporation having a place of business at Locatellikade 1, Parnassustoren, 1076 AZ Amsterdam, The Netherlands, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

- 1) Signature:  Date: MAY 5, 2004
Typed Name: Jeffrey S. Lille
- 2) Signature: _____ Date: _____
Typed Name: Son Van Nguyen
- 3) Signature: _____ Date: _____
Typed Name: Hugo Alberto Emilio Santini

Attny Docket No. HIT1P074/SJ0920010161US1

**ASSIGNMENT OF PATENT APPLICATION**

(Accompanying Application)

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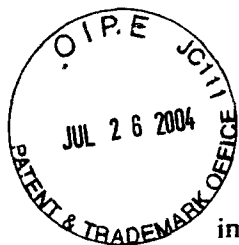
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- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

- 1) Signature: _____ Date: _____
Typed Name: Jeffrey S. Lille
- 2) Signature: Son Van Nguyen Date: May 24, 2004
Typed Name: Son Van Nguyen
- 3) Signature: _____ Date: _____
Typed Name: Hugo Alberto Emilio Santini

Attny Docket No. HIT1P074/SJ0920010161US1

**ASSIGNMENT OF PATENT APPLICATION**

(Accompanying Application)

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Signed on the date(s) indicated beside my (our) signature(s).

- 1) Signature: _____ Date: _____
Typed Name: Jeffrey S. Lille
- 2) Signature: _____ Date: _____
Typed Name: Son Van Nguyen
- 3) Signature: Hugo Alberto Emilio Santini Date: 06/28/2004
Typed Name: Hugo Alberto Emilio Santini

Attny Docket No. HIT1P074/SJ0920010161US1